

REMARKS

In view of the above amendments and the following remarks, reconsideration of the rejections contained in the Office Action of August 5, 2008 is respectfully requested.

By this Amendment, claims 28, 35 and 36 have been amended, and claims 29-34 have been cancelled. Thus, claims 28, 35 and 36 are currently pending in the application. No new matter has been added by these amendments.

On page 2 of the Office Action, the Examiner objected to claims 32 and 33 as being of improper dependent form. In particular, the Examiner indicated that claims 32 and 33 fail to further limit the subject matter of a previous claim. In this regard, it is noted that claims 32 and 33 have been cancelled. Accordingly, it is respectfully submitted that the Examiner's objection is rendered moot.

On pages 2-4 of the Office Action, the Examiner rejected claims 28, 32, 34 and 36 under 35 U.S.C. § 103(a) as being unpatentable over Wakamiya et al. (US 4,833,776). On pages 5-6 of the Office Action, the Examiner rejected claims 29-31, 33 and 35 under 35 U.S.C. § 103(a) as being unpatentable over Wakamiya in view of Fujita (US 4,628,595). For the reasons discussed below, it is respectfully submitted that the amended claims are clearly patentable over the prior art of record.

Amended independent claim 28 recites a method for inserting components to a board. The method of claim 28 includes, at a component grasping position, releasably grasping a first component, having a device portion and a lead wire at the device portion, by applying a first grasping pressure to the device portion of the first component, and while releasably grasping the first component, performing a first positional alignment in a direction along a surface of the board to align the lead wire of the first component and a first lead-wire insertion hole of the board. Further, claim 28 recites, after the performing of the first positional alignment, inserting the lead wire of the first component into the first lead-wire insertion hole of the board, and, at the component grasping position, releasably grasping a second component, having a device portion and a lead wire at the device portion, by applying a second grasping pressure to the device portion of the second component.

The method of claim 28 also includes, while releasably grasping the second component, performing a second positional alignment in a direction along the surface of the board to align

the lead wire of the second component and a second lead-wire insertion hole of the board and, after the performing of the second positional alignment, inserting the lead wire of the second component into the second lead-wire insertion hole of the board.

Claim 28 also recites, for at least one of the first and second components, *correcting an insertion posture of the component* prior to the inserting of the lead wire of the component into the respective one of the first and second lead-wire insertion holes. Further, claim 28 recites that *the correcting of the insertion posture of the component includes grasping the lead wire of the component* and performing positional alignment in a direction along a surface of the board between the lead wire of the component and the respective lead-wire insertion hole of the board, *and grasping the device portion of the component whose lead wire is grasped so as to move the device portion in the direction along the surface of the board about a fulcrum defined at a grasped position of the lead wire to correct a bend of the lead wire such that the device portion is placed at a component insertion position*, and that the first and second components comprise radial components, respectively.

Wakamiya discloses a method which, as shown in Figs. 4A-K, includes fingers 26a, 26b which grab a component 1 by the leads 4 (Fig. 4C) while pushers 22a, 22b are moved downward until they contact the leads 4 (Fig. 4D). Wakamiya also discloses that once the pushers 22a, 22b contact the leads 4, the displacement of each pusher 22a, 22b relative to an interface plate is detected by displacement sensors. Further, Wakamiya discloses that if a lead is bent, two different displacements of the pushers 22a, 22b will be detected, as shown in Fig. 4E, and the component will not be grasped properly. Conversely, Wakamiya discloses that if the displacements of the pushers 22a, 22b are equal, the component has been properly grasped and is ready to be withdrawn from parts tray 31 by the pushers 22a, 22b and fingers 26a, 26b.

However, Wakamiya does not disclose *correcting the insertion posture of the component*, and that the correcting of the insertion posture includes *grasping the lead wire of the component* and performing positional alignment in a direction along a surface of the board between the lead wire of the component and the respective lead-wire insertion hole of the board, *and grasping the device portion of the component whose lead wire is grasped so as to move the device portion in the direction along the surface of the board about a fulcrum defined at a grasped position of the lead wire to correct a bend of the lead wire such that the device portion is placed at a*

component insertion position, as required by independent claim 28.

In this regard, it is first noted that Wakamiya does not disclose correcting the insertion posture of the component. Rather, Wakamiya merely discloses that the displacements of the pushers 22a, 22b are detected by displacement sensors so as to determine whether the component has been properly grasped. In other words, Wakamiya only discloses the detection of an improperly grasped component, and does not disclose correcting the posture of an improperly grasped component.

Therefore, as Wakamiya does not disclose correcting the insertion posture of the component, Wakamiya also does not disclose correcting the insertion posture by grasping the lead wire of the component, and grasping the device portion of the component whose lead wire is grasped so as to move the device portion in the direction along the surface of the board about a fulcrum defined at a grasped position of the lead wire to correct a bend of the lead wire. Further, in addition to the fact that Wakamiya does not disclose correcting the insertion posture of the component, it is also noted that Wakamiya does not disclose that the device portion of the component is grasped, as Wakamiya only discloses that the fingers 26a, 26b grasp the leads. Therefore, Wakamiya does not disclose or even remotely suggest correcting the insertion posture by grasping the lead wire of the component, and grasping the device portion of the component whose lead wire is grasped so as to move the device portion in the direction along the surface of the board about a fulcrum defined at a grasped position of the lead wire to correct a bend of the lead wire, as required by independent claim 28.

Therefore, for the reasons presented above, it is believed apparent that the present invention as recited in independent claim 28 is not disclosed or suggested by the Wakamiya reference. Accordingly, a person having ordinary skill in the art would clearly not have modified the Wakamiya reference in such a manner as to result in or otherwise render obvious the present invention of independent claim 28.

Further, it is noted that Fujita does not cure the defects of the Wakamiya reference with respect to independent claim 28 as discussed above.

Therefore, it is respectfully submitted that independent claim 28, as well as claims 35 and 36 which depend therefrom, are clearly allowable over the prior art of record.

In view of the foregoing amendments and remarks, it is respectfully submitted that the

present application is clearly in condition for allowance. An early notice to that effect is respectfully solicited.

If, after reviewing this Amendment, the Examiner feels there are any issues remaining which must be resolved before the application can be passed to issue, the Examiner is respectfully requested to contact the undersigned by telephone in order to resolve such issues.

Respectfully submitted,

Shozo KADOTA et al.

/Kenneth W. Fields/
By: 2008.12.05 13:28:18 -05'00'
Kenneth W. Fields
Registration No. 52,430
for
Walter C. Pledger
Registration No. 55,540
Attorney for Applicants

WCP/KWF/lkd
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
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